



**DGD2181** 

### Description

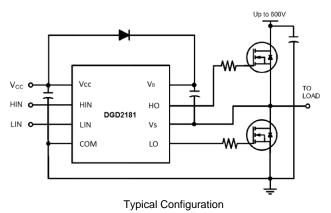
The DGD2181 is a high voltage / high speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD2181's high-side to switch to 600V in a bootstrap operation.

The DGD2181 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction.

The DGD2181 is offered in SO-8 (Type TH) package and the operating temperature extends from -40°C to +125°C.

### Applications

- **DC-DC** Converters
- **DC-AC** Inverters
- **AC-DC Power Supplies**
- Motor Controls
- **Class D Power Amplifiers**



### Ordering Information (Note 4)

Part number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DGD2181S8-13	DGD2181	13	12	2,500

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### Marking Information

Notes:



= Manufacturer's Marking CH DGD2181 = Product Type Marking Code = Year (ex: 16 = 2016) YY WW

= Week (01 to 53)

HIGH-SIDE AND LOW-SIDE GATE DRIVER IN SO8

### Features

- Floating High-side Driver in Bootstrap Operation to 600V
- Drives two N-Channel MOSFETs or IGBTs in a Half Bridge Configuration
- 1.9A Source / 2.3A Sink Output Current Capability
- **Outputs Tolerant to Negative Transients**
- Wide Low-side Gate Driver and Logic Supply: 10V to 20V •
- Logic Input (HIN and LIN) 3.3V Capability
- Schmitt Triggered Logic Inputs with Internal Pull Down
- Undervoltage Lockout for High and Low Side Drivers
- Extended Temperature Range: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

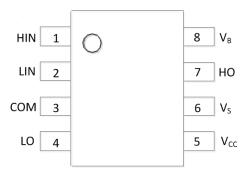
### **Mechanical Data**

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.075 grams (Approximate)



SO-8 (Type TH) Top View



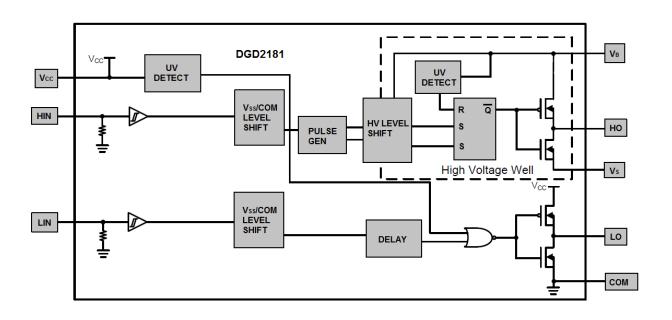


Top View SO-8 (Type TH)

# **Pin Descriptions**

Pin Number	Pin Name	Function
1	HIN	Logic input for high-side gate driver output, in phase with HO
2	LIN	Logic input for low-side gate driver output, in phase with LO
3	COM	Low-side and logic return
4	LO	Low-side gate drive output
5	Vcc	Low-side and logic fixed supply
6	Vs	High-side floating supply return
7	HO	High-side gate drive output
8	VB	High-side floating supply

# **Functional Block Diagram**





# Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
High-side Floating Supply Voltage	VB	-0.3 to +624	V	
High-side Floating Supply Offset Voltage	Vs	V <sub>B</sub> -24 to V <sub>B</sub> +0.3	V	
High-side Floating Output Voltage	V <sub>HO</sub>	V <sub>S</sub> -0.3 to V <sub>B</sub> +0.3	V	
Offset Supply Voltage Transient	dVs / dt	50	V/ns	
Low-side Fixed Supply Voltage	V <sub>CC</sub>	-0.3 to +24	V	
Low-side Output Voltage	V <sub>LO</sub>	-0.3 to V <sub>CC</sub> +0.3	V	
Logic Input Voltage (HIN and LIN)	V <sub>IN</sub>	-0.3 to V <sub>CC</sub> +0.3	V	

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	PD	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>0JA</sub>	200	°C/W
Operating Temperature	TJ	+150	
Lead Temperature (Soldering, 10s)	TL	+300	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

## **Recommended Operating Conditions**

Parameter	Symbol	Min	Max	Unit
High side Floating Supply Absolute Voltage	VB	V <sub>S</sub> + 10	V <sub>S</sub> + 20	V
High side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High side Floating Output Voltage	V <sub>HO</sub>	Vs	VB	V
Low Side Fixed Supply Voltage	Vcc	10	20	V
Low Side Output Voltage	VLO	0	Vcc	V
Logic Input Voltage (HIN and LIN)	V <sub>IN</sub>	0	5	V
Ambient Temperature	T <sub>A</sub>	-40	+125	°C

Note: 6. Logic operation for  $V_S$  of -5V to +600V. Logic state held for  $V_S$  of -5V to - $V_{BS}$ .



# **DC Electrical Characteristics** ( $V_{BIAS}$ ( $V_{CC}$ , $V_{BS}$ ) = 15V, $@T_A = +25^{\circ}C$ , unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" Input Voltage	VIH	2.5	_	-	V	V <sub>CC</sub> = 10V to 20V
Logic "0" Input Voltage	VIL	-	-	0.8	V	$V_{CC} = 10V$ to 20V
High Level Output Voltage, V <sub>BIAS</sub> - V <sub>O</sub>	Vон	_	-	1.4	V	$I_O = 0 m A$
Low Level Output Voltage, V <sub>O</sub>	V <sub>OL</sub>	_	-	0.2	V	I <sub>O</sub> = 20mA
Offset Supply Leakage Current	I <sub>LK</sub>	-	-	50	μA	$V_{B} = V_{S} = 600V$
Quiescent V <sub>BS</sub> Supply Current	I <sub>BSQ</sub>	20	60	150	μA	$V_{IN} = 0V \text{ or } 5V$
Quiescent V <sub>CC</sub> Supply Current	ICCQ	50	120	240	uA	$V_{IN} = 0V \text{ or } 5V$
Logic "1" Input Bias Current	I <sub>IN+</sub>	-	25	60	μA	$V_{IN} = 5V$
Logic "0" Input Bias Current	I <sub>IN-</sub>	-	-	5.0	μA	$V_{IN} = 0V$
V <sub>BS</sub> Supply Under-voltage Positive Going Threshold	V <sub>BSUV+</sub>	8.0	8.9	9.8	V	-
V <sub>BS</sub> Supply Under-voltage Negative Going Threshold	V <sub>BSUV-</sub>	7.4	8.2	9.0	V	-
V <sub>CC</sub> Supply Under-voltage Positive Going Threshold	V <sub>CCUV+</sub>	8.0	8.9	9.8	V	-
V <sub>CC</sub> Supply Under-voltage Negative Going Threshold	V <sub>CCUV</sub> -	7.4	8.2	9.0	V	-
Output High Short Circuit Pulsed Current	I <sub>O+</sub>	1.4	1.9	-	Α	V <sub>O</sub> = 0V, PW ≤ 10µs
Output Low Short Circuit Pulsed Current	I <sub>O-</sub>	1.7	2.3	-	А	V <sub>O</sub> = 15V, PW ≤ 10µs

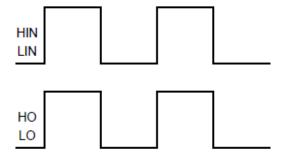
Note: 7. The V<sub>IN</sub> and I<sub>IN</sub> parameters are applicable to the two logic input pins: LIN and HIN. The V<sub>0</sub> and I<sub>0</sub> parameters are applicable to the respective output pins: HO and LO.

## AC Electrical Characteristics (V<sub>BIAS</sub> (V<sub>CC</sub>, V<sub>BS</sub>) = 15V, C<sub>L</sub> = 1000pF, @T<sub>A</sub> = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-on Propagation Delay	ton	-	180	270	ns	$V_{S} = 0V$
Turn-off Propagation Delay	t <sub>OFF</sub>	-	220	330	ns	$V_{\rm S} = 0V \text{ or } 600V$
Delay Matching, HO & LO Turn-on/off	t <sub>DM</sub>	-	-	35	ns	-
Turn-on Rise Time	t <sub>R</sub>	-	40	60	ns	$V_{\rm S} = 0V$
Turn-off Fall Time	tF	-	20	35	ns	$V_{\rm S} = 0V$



# **Timing Waveforms**



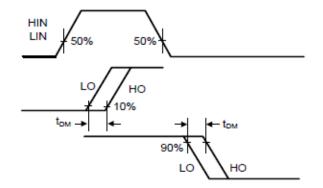


Figure 1. Input / Output Timing Diagram

Figure 2. Delay Matching Waveform Definitions

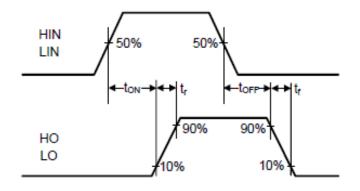


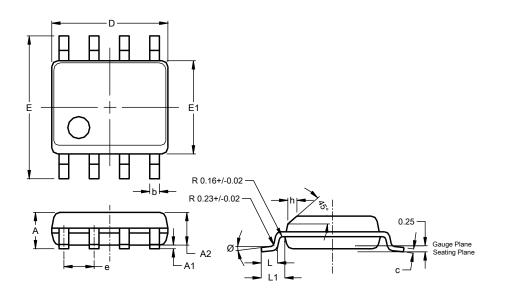
Figure 3. Switching Time Waveform Definitions



DGD2181

## **Package Outline Dimensions**

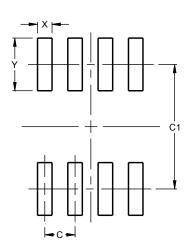
Please see http://www.diodes.com/package-outlines.html for the latest version.



	SO-8 (Type TH)					
Dim	Min	Max	Тур			
Α	1.35	1.75				
A1	0.10	0.25				
A2			1.45			
b	0.35	0.51				
c	0.190	0.248				
D	4.80	5.00	4.90			
Е	5.80	6.20	6.00			
E1	3.80	4.00	3.90			
e			1.27			
h	0.25	0.50				
L	0.41	1.27				
L1			1.04			
Ø	0°	8°				
All [	All Dimensions in mm					

## Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8 (Type TH)

Dimensions	Value (in mm)
С	1.27
C1	5.20
Х	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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